



Material Content Data Sheet



Sales Product Name		TLE5012B E3005		Issued		25. September 2017		
MA#		MA000983866						
Package		PG-DSO-8-16		Weight*		83.55 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.535	4.23	4.23	42306	42306
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107	
	non noble metal	zinc	7440-66-6	0.036	0.04		429	
	non noble metal	iron	7439-89-6	0.717	0.86		8584	
wire	non noble metal	copper	7440-50-8	29.121	34.86	35.77	348559	357679
	noble metal	gold	7440-57-5	0.154	0.18	0.18	1840	1840
	encapsulation	organic material	carbon black	1333-86-4	0.094	0.11		1124
encapsulation	plastics	epoxy resin	-	4.321	5.17		51714	
	inorganic material	silicondioxide	60676-86-0	42.548	50.93	56.21	509276	562114
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9741	9741
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7783	7783
glue	plastics	acrylic resin	-	0.341	0.41		4078	
	noble metal	silver	7440-22-4	1.208	1.45	1.86	14459	18537
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com